Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Over-Voltage Protection
- Low Forward Voltage Drop
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These are Pb-Free Devices

Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings:
 - ◆ Machine Model = C
 - ♦ Human Body Model = 3B



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SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 60 VOLTS



SMB CASE 403A

MARKING DIAGRAM



B26 = Specific Device Code A = Assembly Location**

Y = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRS260T3G, NRVBS260T3G*, NRVBS260T3G-VF01*	SMB (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V	
Average Rectified Forward Current (At Rated V_R , $T_L = 95^{\circ}C$)	Io	2.0	А	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	60	А	
Storage Temperature Range	T _{stg}	-55 to +150	°C	
Operating Junction Temperature	TJ	-55 to +125	°C	
Voltage Rate of Change (Rated V_R , $T_J = 25^{\circ}C$)	dv/dt	10,000	V/μs	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJL} \ R_{ hetaJA}$	24 80	°C/W

^{1.} Mounted with minimum recommended pad size, PC Board FR4.

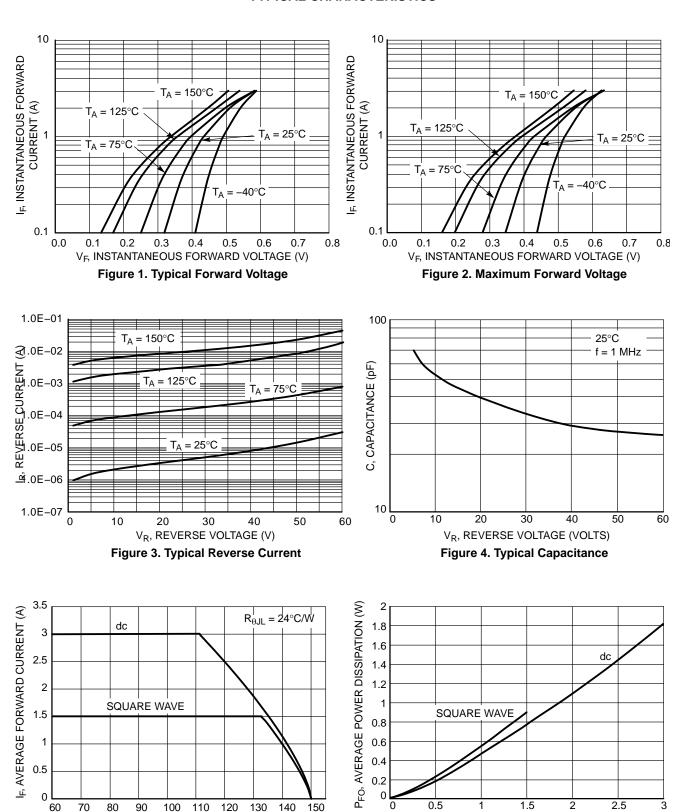
ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 3)	VF	T _J = 25°C	T _J = 125°C	V
$(i_F = 1.0 \text{ A})$ $(i_F = 2.0 \text{ A})$		0.51 0.63	0.475 0.55	
Maximum Instantaneous Reverse Current (Note 3)	I _R	T _J = 25°C	T _J = 125°C	mA
(V _R = 60 V)		0.2	20	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2.0%.

^{2. 1} inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

TYPICAL CHARACTERISTICS



I_O, AVERAGE FORWARD CURRENT (AMPS)

Figure 6. Forward Power Dissipation

T_L, LEAD TEMPERATURE (°C)

Figure 5. Current Derating - Junction to Lead

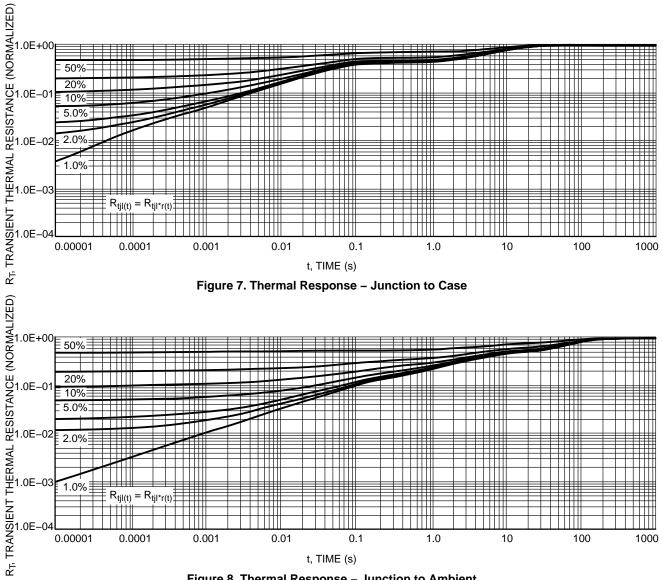


Figure 7. Thermal Response - Junction to Case

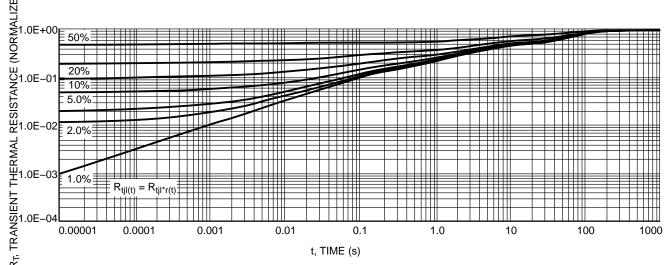
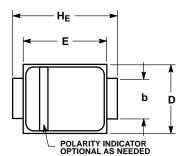
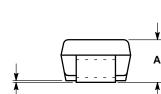


Figure 8. Thermal Response - Junction to Ambient

PACKAGE DIMENSIONS

SMB CASE 403A-03 ISSUE J





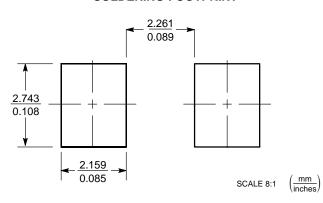
A1

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	L1 0.51 REF			0.020 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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